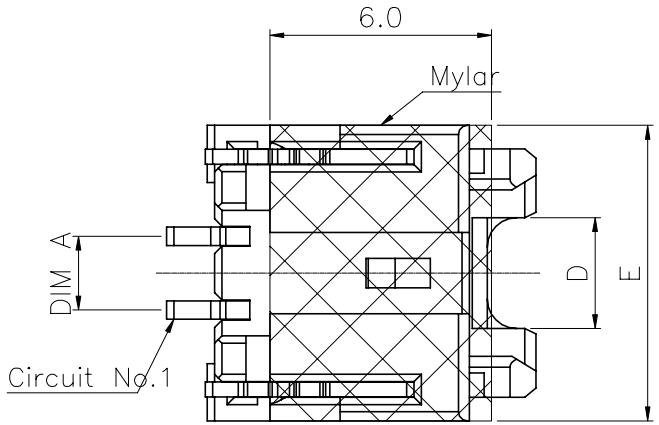
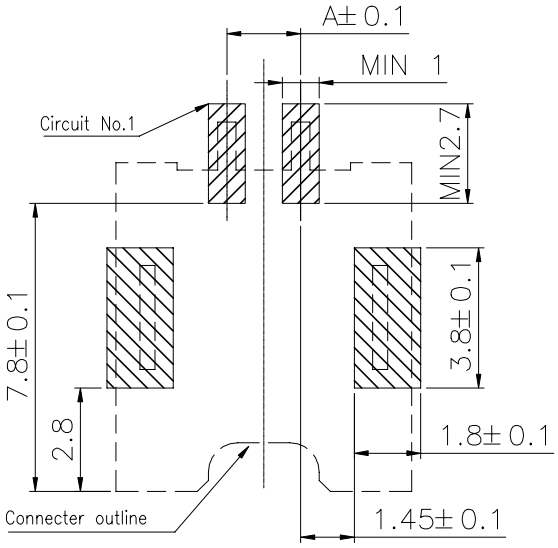
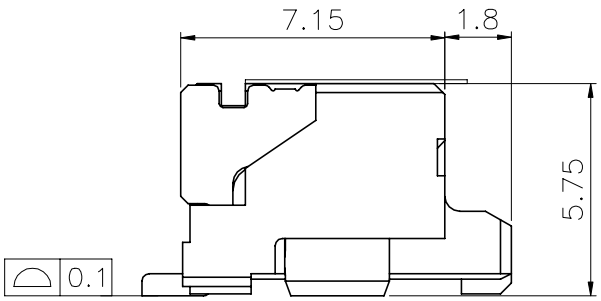


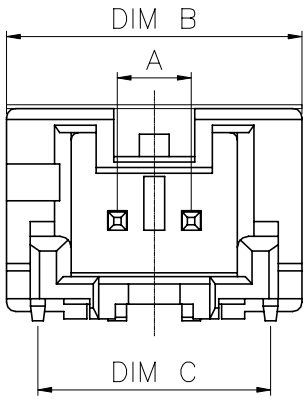


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

NOTES:
1. MATERIAL:
   1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:NATURAL.
   1.2 CONTACT: COPPER ALLOY
   1.3 FITTING NAIL: COPPER ALLOY
2. FINISH:
   2.1 CONTACT:
   80u"MIN. MATT TIN PLATING OVERALL,
   50u" MIN. NICKEL UNDERPLATING OVERALL.
   2.2 FITTING NAIL:
   80u"MIN. MATT TIN PLATING OVERALL,
   50u" MIN. NICKEL UNDERPLATING OVERALL.
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-51355-XXXXX-XXX
5. PACKAGE PLS. REFER TO 51355-XXXX-XX-TRP
6. PART NUMBER

51355-XXX X X-XXX
- NO OF CKT
- PACKING: 4:TAPE & REEL WITH MYLAR
- PLATING: N: MATT Tin
- 001:NORMAL





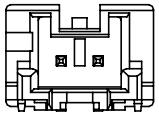
CKT	Dim A	Dim B	Dim C	Dim D	Dim E
2	2.0	8.0	6.3	3.0	8.0
3	4.0	10.0	8.3	5.0	9.0
4	6.0	12.0	10.3	6.0	11.0
5	8.0	14.0	12.3	8.0	13.0
6	10.0	16.0	14.3	10.0	15.0
7	12.0	18.0	16.3	12.0	17.0
8	14.0	20.0	18.3	14.0	19.0
9	16.0	22.0	20.3	16.0	21.0
10	18.0	24.0	22.3	18.0	23.0
11	20.0	26.0	24.3	20.0	25.0
12	22.0	28.0	26.3	22.0	27.0
13	24.0	30.0	28.3	24.0	29.0

QUALITY SYMBOLS
MAJOR Ⓜ
CRITICAL Ⓒ

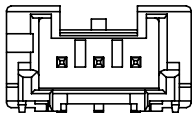
GENERAL TOLERANCES (UNLESS SPECIFIED)
X. ±0.5
.X ±0.25
.XX ±0.15
.XXX ±0.1
ANGLES ±2°

DRAWN BY: Rong, Li Ping	DATE: 22'/09/01	ACES ELECTRONICS
CHECKED BY: Lu,Jing Quan	DATE: 22'/09/01	TITLE: 2.00 mm PITCH WAFER CONN. SMT S/R R/A TYPE
APPROVED BY: Hsieh,Fu Yu	DATE: 22'/09/01	
UNITS: mm		SIZE: A4
SCALE: 5 : 1	SHEET NO.: 1 OF 2	REV: D

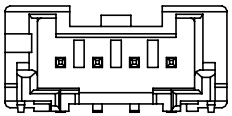
RFQ NO.	N/A
PART NO.	SEE NOTES
DWG NO.	51355-XXXXX-XXX



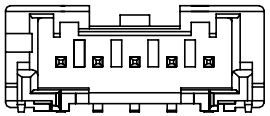
2 PIN



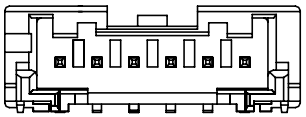
3 PIN



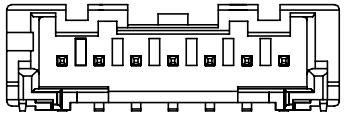
4 PIN



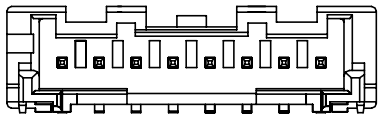
5 PIN



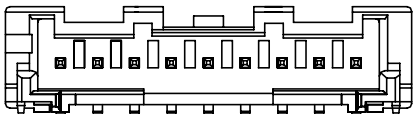
6 PIN



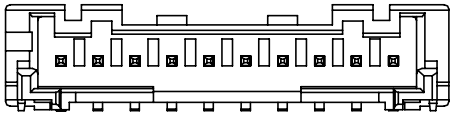
7 PIN



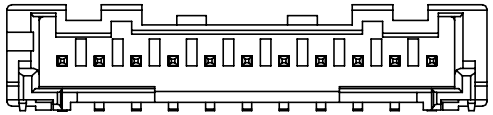
8 PIN



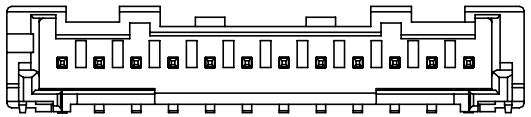
9 PIN



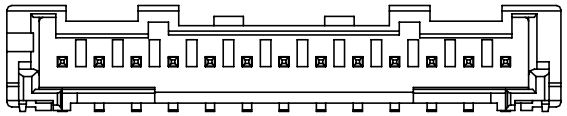
10 PIN



11 PIN



12 PIN



13 PIN

SCALE 2:1

QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓒ	DRAWN BY: Rong, Li Ping — DATE: 22'/09/01	ACES ELECTRONICS	
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	CHECKED BY: Lu,Jing Quan — DATE: 22'/09/01 APPROVED BY: Hsieh,Fu Yu — DATE: 22'/09/01	TITLE: 2.00 mm PITCH WAFER CONN. SMT S/R R/A TYPE	
	UNITS: mm	SIZE: A4	RFQ NO.: N/A
	SCALE: 5 : 1 — SHEET NO.: 2 OF 2	REV: D	PART NO.: SEE NOTES DWG NO.: 51355-XXXXX-XXX